



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 10/761,784
Applicant: Wei Pan *et al.*
Filed: January 21, 2004
Group #: 2823
Examiner: William D. Coleman

Confirmation Number: 3531

Docket No: SLA.0861
Customer No: 27518
For: Integrated Circuit Structure with Copper Interconnect

MS AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

**RESPONSE TO OFFICE ACTION UNDER 37 C.F.R. § 1.111
CHANGE OF CORRESPONDENCE ADDRESS
Introductory Comments**

In response to the Office Action dated April 15, 2005, please amend the above-identified Application as follows:

Amendment to the Specification None

Amendment to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Amendment to the Drawings None

Remarks/Arguments begin on page 9 of this paper.

An **Appendix** is not included.